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**(54) EPOXY RESIN COMPOSITION**

**(57) Abstract**

**PURPOSE:** To obtain the title composition useful as a matrix resin for high-performance composite material, suitable for prepreg having excellent storage stability, comprising a tetrafunctional epoxy resin as a main component and a specific diaminodiphenylsulfone as a curing agent.

**CONSTITUTION:** Diaminodiphenylsulfone(DDS)

containing  $\approx 50\text{wt}\%$  particles having  $\leq 13\mu\text{m}$  particle diameter as a curing agent is dispersed in a granular state into a tetrafunctional epoxy resin as a main component and optionally the blend is mixed with a curing promoter such as imidazole compound,  $< 50\text{wt}\%$  another epoxy resin (bisphenol A type epoxy resin), a thermoplastic resin, a filler, etc., to give the aimed composition. The amount of active hydrogen of amine of DDS blended is 0.4-1.5 equivalent based on epoxy group.

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